



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS} (@ T _J Max) (Note 7)	R _{DS(ON)}	I _D T _C = +25°C
1000V	2.2Ω@V _{GS} = 10V	6A

Description

This new generation MOSFET features low on-resistance and fast switching, making it ideal for high efficiency power management applications.

Applications

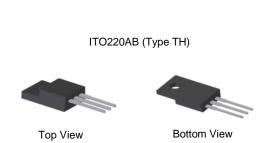
- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

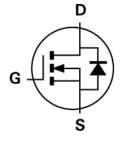
Features

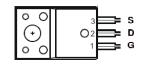
- Low Input Capacitance
- High BV_{DSS} Rating for Power Application
- Low Input/Output Leakage
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: ITO220AB (Type TH)
- Case Material: Molded Plastic, "Green" Molding Compound, UL Flammability Classification Rating 94V-0
- Terminals: Matte Tin Finish Annealed Over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Terminal Connections: See Diagram Below
- Weight: 1.85 grams (Approximate)







Equivalent Circuit

Top View Pin Out Configuration

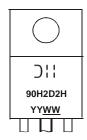
Ordering Information (Note 4)

- 7					
	Part Number	Case	Packaging		
	DMN90H2D2HCTI	ITO220AB (Type TH)	50 Pieces/Tube		

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



☐ Hamaufacturer's Marking

90H2D2H = Product Type Marking Code

YYWW = Date Code Marking

YY or YY = Last Two Digits of Year (ex: 16 = 2016)

WW or WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	900	V
Gate-Source Voltage		V_{GSS}	±30	V
Continuous Drain Current (Notes 5)	T _C = +25°C	-	6	Δ
V _{GS} = 10V (Note 6)	$T_{C} = +100^{\circ}C$	ID	4	^
Pulsed Drain Current		I _{DM}	24	Α
Avalanche Current, L = 60mH (Note 7)		I _{AS}	3.5	Α
Avalanche Energy, L = 60mH (Note 7)		E _{AS}	360	mJ

Thermal Characteristics

Characteristic		Symbol	Max	Unit
Power Dissipation (Note 5)	$T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$	P_{D}	40 14	W
Thermal Resistance, Junction to Case (Note 5)	$T_C = +25$ °C	$R_{\theta JC}$	3.6	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

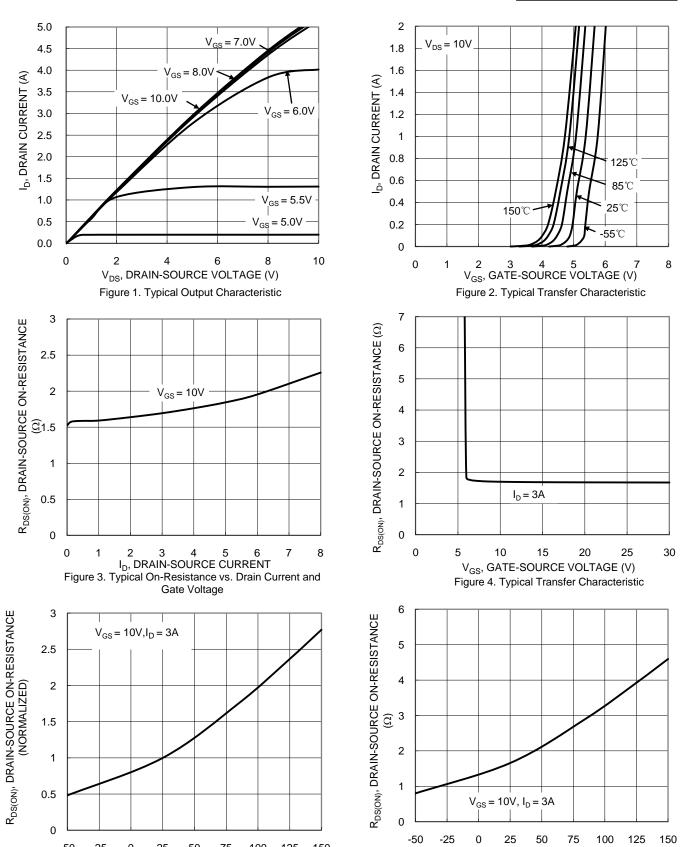
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Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	900		_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μA	$V_{DS} = 900V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	100	nA	$V_{GS} = \pm 30V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	3	4	5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	1.7	2.2	Ω	$V_{GS} = 10V, I_D = 3A$	
Diode Forward Voltage	V _{SD}	_	0.85	1.2	V	$V_{GS} = 0V$, $I_S = 6A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C _{iss}	_	1487	_		\\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Output Capacitance	Coss	_	113	_	pF	$V_{DS} = 25V$, $f = 1MHz$, $V_{GS} = 0V$	
Reverse Transfer Capacitance	C _{rss}	_	1	_			
Gate Resistance	Rg	_	4.7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Q_g	_	20.3	_		V _{DD} = 720V, I _D = 6A, V _{GS} = 10V	
Gate-Source Charge	Q _{gs}	_	6.4	_	nC		
Gate-Drain Charge	Q_{gd}	_	6.1	_			
Turn-On Delay Time	t _{D(ON)}	_	39	_	- ns	$V_{DD} = 450V, V_{GS} = 10V,$ $R_g = 25\Omega, I_D = 6A$	
Turn-On Rise Time	t _R	_	49	_			
Turn-Off Delay Time	t _{D(OFF)}	_	51	_			
Turn-Off Fall Time	t _F	_	31	_			
Body Diode Reverse Recovery Time	t _{RR}	_	607	_	ns	I _F = 6A, dl/dt = 100A/μs	
Body Diode Reverse Recovery Charge	Q _{RR}	_	8.1	_	μC	71F = 0A, αί/αι = 100A/μ5	

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Drain current limited by maximum junction temperature.
- 7. Guaranteed by design. Not subject to production testing. 8. Short duration pulse test used to minimize self-heating effect.







0

25

50

T_J, JUNCTION TEMPERATURE (°C)
Figure 5. On-Resistance Variation with Junction

Temperature

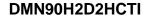
75

100

150

 T_J , JUNCTION TEMPERATURE ($^{\circ}$)

Figure 6. On-Resistance Variation with Junction Temperature





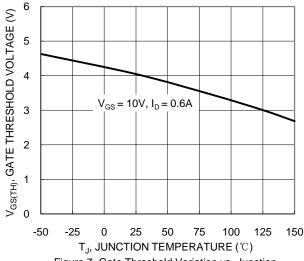
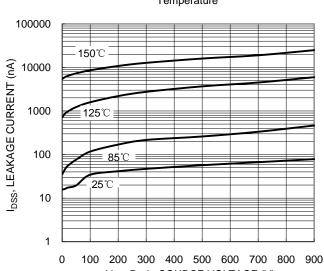
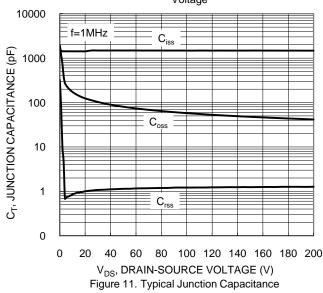


Figure 7. Gate Threshold Variation vs. Junction Temperature



V_{DS}, Drain-SOURCE VOLTAGE (V) Figure 9. Typical Drain-Source Leakage Current vs. Voltage



5 4.5 $V_{GS} = 0V$ 4 IS, SOURCE CURRENT (A) 3.5 3 2.5 2 $T_J = 85^{\circ}C$ 1.5 $T_J = 125^{\circ}C$ 1 $\Gamma_{\rm J} = 25^{\circ}\rm C$ $T_{J} = 150^{\circ}C$ 0.5 $T_1 = -55^{\circ}C$ 0 0 0.3 0.6 0.9 1.2 V_{SD}, SOURCE-DRAIN VOLTAGE (V)

Figure 8. Diode Forward Voltage vs. Current

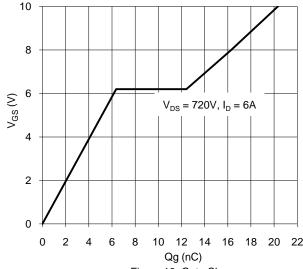


Figure 10. Gate Charge

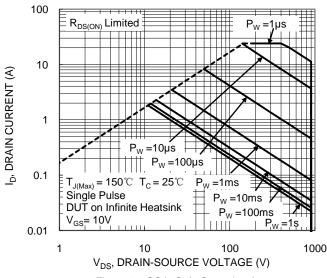
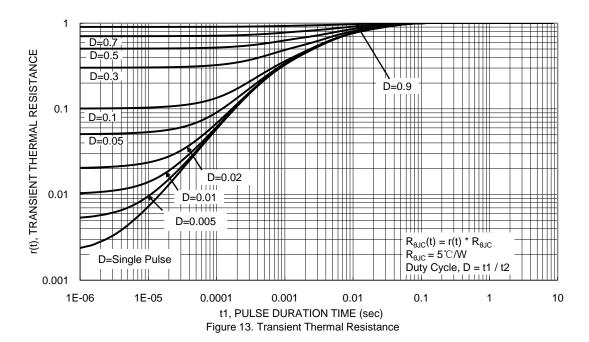


Figure 12. SOA, Safe Operation Area



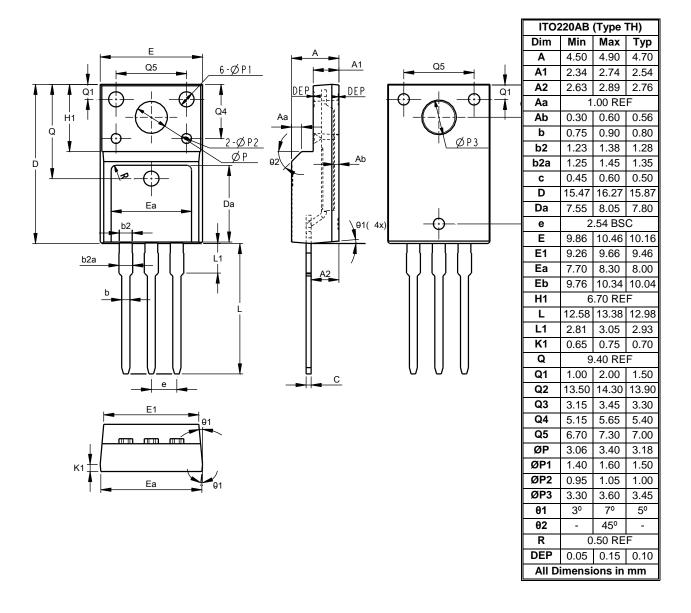




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

ITO220AB (Type TH)





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